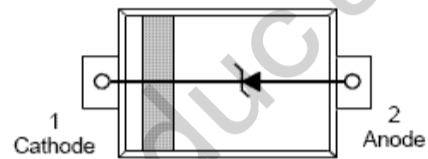


Features

- ◆ 150W (8x20us) Peak Pulse Power
- ◆ Low Clamping Voltage
- ◆ SOD-523 Package
- ◆ RoHS Compliant
- ◆ Matte Tin Lead finish (Pb-Free)
- ◆ Protect One I/O or Power Line
- ◆ Meet IEC61000-4-2 Level 4:
Contact Discharge > 8kV
Air Discharge > 15kV



SOD-523

Applications

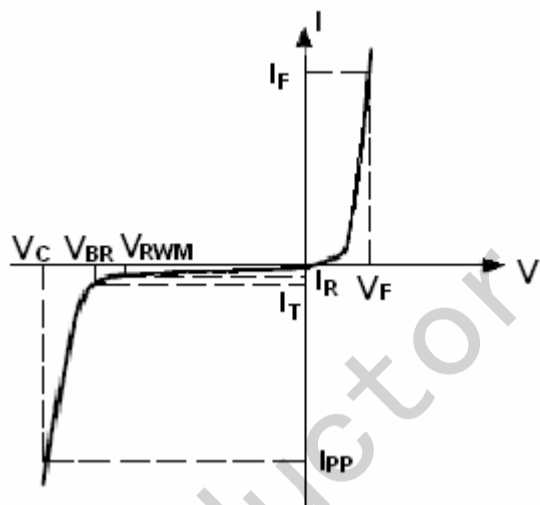
- ◆ Smart Phones
- ◆ Laptop Computers
- ◆ Portable Electronics

Maximum Ratings (Ta = 25°C)

Symbol	Parameter	Value	Unit
TJ	Junction Temperature	-55 to +150	°C
TSTG	Storage Temperature	-55 to +150	°C
Ipp Max	Maximum Peak Pulse Current	2	A
PPK	Peak Pulse Power	150	W

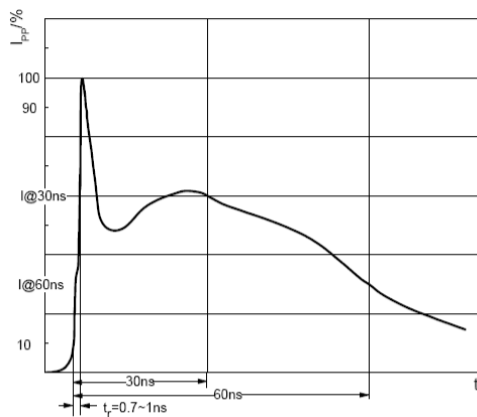
Electrical Parameter

Symbol	Parameter
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Working Peak Reverse Voltage
I_R	Maximum Reverse Leakage Current @ V_{RWM}
I_T	Test Current
V_{BR}	Breakdown Voltage @ I_T
I_F	Forward Current
V_F	Forward Voltage @ I_F

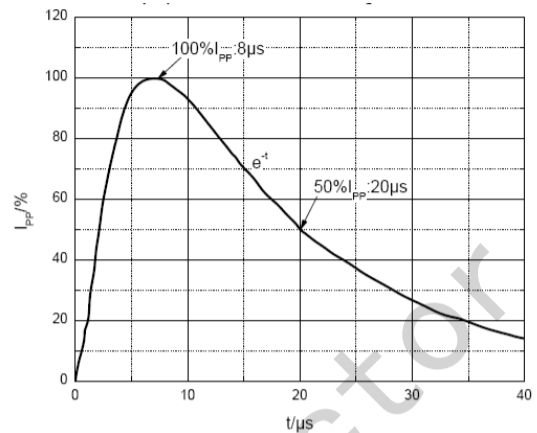


Electrical Characteristics (Ta = 25°C)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{RWM}	Reverse Working Peak Voltage				36	V
V_{BR}	Reverse Breakdown Voltage	$I_T = 1\text{mA}$	40	43	48	V
I_R	Reverse Leakage Current	$V_{RWM} = 36\text{V}$			1	μA
V_C	Clamping Voltage	$I_{PP} = 2\text{A}$ (8/20 μs)			80	V
I_{pp}	Peak Pulse Current	$t_p = 8/20\mu\text{s}$			2	A
C_J	Capacitance	$V_R = 0\text{V}$, $f = 1\text{MHz}$		20		pF

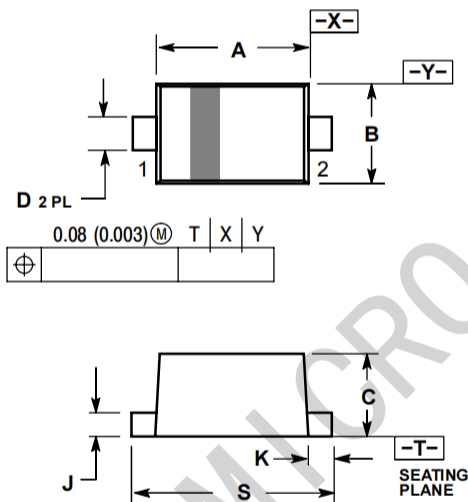


ESD pulse waveform according to IEC61000-4-2



8/20us pulse waveform according to IEC 61000-4-5

SOD-523



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.10	1.20	1.30	0.043	0.047	0.051
B	0.70	0.80	0.90	0.028	0.032	0.035
C	0.50	0.60	0.70	0.020	0.024	0.028
D	0.25	0.30	0.35	0.010	0.012	0.014
J	0.07	0.14	0.20	0.0028	0.0055	0.0079
K	0.15	0.20	0.25	0.006	0.008	0.010
S	1.50	1.60	1.70	0.059	0.063	0.067

SOLDERING FOOTPRINT*

